Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	3 X 3 X 0.75 (1.5 EP)
Lead Count	16
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	1.21E-02	86.2	862000	35.26	352639
Thermosets	Epoxy resin	Proprietary	8.40E-04	6.0	60000	2.45	24546
Thermosets	Phenol resin	Proprietary	8.40E-04	6.0	60000	2.45	24546
Other inorganic materials	Metal Hydroxide	Proprietary	2.10E-04	1.5	15000	0.61	6136
Other inorganic materials	Carbon black	1333-86-4	4.20E-05	0.3	3000	0.12	1227
Subtotal			1.40E-02	100.00	1000000	40.91	409094

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.64 E-02	97.50	975000	47.86	478639
Copper & its alloys	Iron	7439-89-6	3.95 E-04	2.35	23500	1.15	11536
Copper & its alloys	Zinc	7440-66-6	2.02 E-05	0.12	1200	0.06	589
Copper & its alloys	Phosphorus	7723-14-0	5.04 E-06	0.03	300	0.01	147
Subtotal			1.68 E-02	100.00	1000000	49.09	490912

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	4.20 E-05	100.0	1000000	0.12	1227

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	8.00 E-04	100.0	1000000	2.34	23377

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	8.00 E-05	100.0	1000000	0.23	2338

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.40 E-03	100.0	1000000	7.01	70130

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.77 E-05	77.71	777100	0.23	2271
Thermoset	Epichlorohydrin-formaldehyde-phenol copolymer	9003-36-5	3.11 E-06	3.11	31100	0.01	91
Other organic materials	Epoxy resin, epichlorohydrin-dimer fatty acid	68475-94-5	3.11 E-06	3.11	31100	0.01	91
Other organic materials	Butyrolactone, gamma-	96-48-0	3.11 E-06	3.11	31100	0.01	91
Other organic materials	Poly(oxypropylene)diamine	9046-10-0	3.11 E-06	3.11	31100	0.01	91
Other organic materials	2,6-Diglycidyl phenyl allyl ether oligomer	Unassigned	3.11 E-06	3.11	31100	0.01	91
Other organic materials	Organosilane	TS ref# 10001	3.11 E-06	3.11	31100	0.01	91
Other inorganic materials	Copper(II) oxide	1317-38-0	3.11 E-06	3.11	31100	0.01	91
Other organic materials	Epoxy resin modifier	TS ref# 10038	5.20 E-07	0.52	5200	0.002	15
Subtotal			1.00 E-04	100.0	1000000	0.29	2922

	Weight (g)	Percentage (%)	PPM
Package Totals	**3.42 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.